

# SN74AC240-Q1 OCTAL BUFFER/DRIVER WITH 3-STATE OUTPUTS

SCAS785A – OCTOBER 2004 – REVISED JANUARY 2008

- Qualified for Automotive Applications
- 2-V to 6-V  $V_{CC}$  Operation
- Inputs Accept Voltages to 6 V
- Max  $t_{pd}$  of 6.5 ns at 5 V

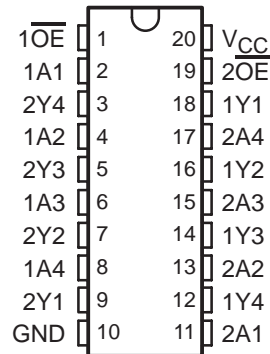
## description/ordering information

This octal buffer and line driver is designed specifically to improve the performance and density of 3-state memory address drivers, clock drivers, and bus-oriented receivers and transmitters.

The SN74AC240 device is organized as two 4-bit buffers/drivers with separate output-enable ( $\overline{OE}$ ) inputs. When  $\overline{OE}$  is low, the device passes inverted data from the A inputs to the Y outputs. When  $\overline{OE}$  is high, the outputs are in the high-impedance state.

To ensure the high-impedance state during power up or power down,  $\overline{OE}$  should be tied to  $V_{CC}$  through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

DW OR PW PACKAGE  
(TOP VIEW)



## ORDERING INFORMATION†

$T_A$	PACKAGE‡		ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 125°C	SOIC – DW	Tape and reel	SN74AC240QDWRQ1	AC240Q
	TSSOP – PW	Tape and reel	SN74AC240QPWRQ1	AC240Q

† For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at [www.ti.com](http://www.ti.com).

‡ Package drawings, thermal data, and symbolization are available at [www.ti.com/packaging](http://www.ti.com/packaging).

FUNCTION TABLE  
(each buffer)

INPUTS		OUTPUT
$\overline{OE}$	A	Y
L	H	L
L	L	H
H	X	Z



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PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

 **TEXAS  
INSTRUMENTS**

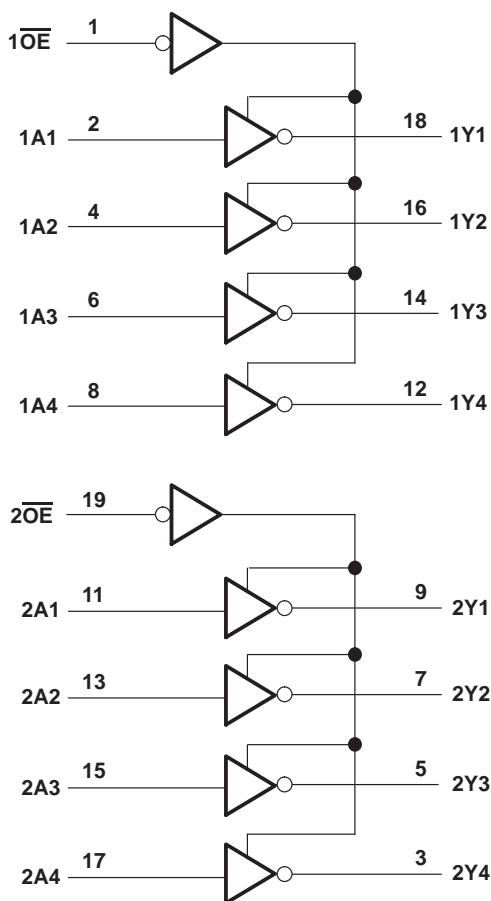
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## logic diagram (positive logic)



## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, $V_{CC}$ .....	-0.5 V to 7 V
Input voltage range, $V_I$ (see Note 1) .....	-0.5 V to $V_{CC} + 0.5$ V
Output voltage range, $V_O$ (see Note 1) .....	-0.5 V to $V_{CC} + 0.5$ V
Input clamp current, $I_{IK}$ ( $V_I < 0$ or $V_I > V_{CC}$ ) .....	$\pm 20$ mA
Output clamp current, $I_{OK}$ ( $V_O < 0$ or $V_O > V_{CC}$ ) .....	$\pm 20$ mA
Continuous output current, $I_O$ ( $V_O = 0$ to $V_{CC}$ ) .....	$\pm 50$ mA
Continuous current through $V_{CC}$ or GND .....	$\pm 200$ mA
Package thermal impedance, $\theta_{JA}$ (see Note 2): DW package .....	58°C/W
..... PW package .....	83°C/W
Storage temperature range, $T_{stg}$ .....	-65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.  
2. The package thermal impedance is calculated in accordance with JESD 51-7.



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## recommended operating conditions (see Note 3)

		MIN	MAX	UNIT
$V_{CC}$	Supply voltage	2	6	V
$V_{IH}$	High-level input voltage	$V_{CC} = 3\text{ V}$	2.1	V
		$V_{CC} = 4.5\text{ V}$	3.15	
		$V_{CC} = 5.5\text{ V}$	3.85	
$V_{IL}$	Low-level input voltage	$V_{CC} = 3\text{ V}$	0.9	V
		$V_{CC} = 4.5\text{ V}$	1.35	
		$V_{CC} = 5.5\text{ V}$	1.65	
$V_I$	Input voltage	0	$V_{CC}$	V
$V_O$	Output voltage	0	$V_{CC}$	V
$I_{OH}$	High-level output current	$V_{CC} = 3\text{ V}$	-12	mA
		$V_{CC} = 4.5\text{ V}$	-24	
		$V_{CC} = 5.5\text{ V}$	-24	
$I_{OL}$	Low-level output current	$V_{CC} = 3\text{ V}$	12	mA
		$V_{CC} = 4.5\text{ V}$	24	
		$V_{CC} = 5.5\text{ V}$	24	
$\Delta t/\Delta v$	Input transition rise or fall rate		8	ns/V
$T_A$	Operating free-air temperature	-40	125	°C

NOTE 3: All unused inputs of the device must be held at  $V_{CC}$  or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

# SN74AC240-Q1

## OCTAL BUFFER/DRIVER

### WITH 3-STATE OUTPUTS

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V <sub>CC</sub>	T <sub>A</sub> = 25°C			T <sub>A</sub> = -40°C TO 125°C		T <sub>A</sub> = -40°C TO 85°C		UNIT	
			MIN	TYP	MAX	MIN	MAX	MIN	MAX		
V <sub>OH</sub>	I <sub>OH</sub> = -50 μA	3 V	2.9			2.9		2.9		V	
		4.5 V	4.4			4.4		4.4			
		5.5 V	5.4			5.4		5.4			
	I <sub>OH</sub> = -12 mA	3 V	2.56			2.4		2.46			
	I <sub>OH</sub> = -24 mA	4.5 V	3.86			3.7		3.76			
		5.5 V	4.86			4.7		4.76			
	I <sub>OH</sub> = -50 mA†	5.5 V				3.85					
I <sub>OH</sub> = -75 mA†	5.5 V						3.85				
V <sub>OL</sub>	I <sub>OL</sub> = 50 μA	3 V	0.1			0.1		0.1		V	
		4.5 V	0.1			0.1		0.1			
		5.5 V	0.1			0.1		0.1			
	I <sub>OL</sub> = 12 mA	3 V	0.36			0.5		0.44			
	I <sub>OL</sub> = 24 mA	4.5 V	0.36			0.5		0.44			
		5.5 V	0.36			0.5		0.44			
	I <sub>OL</sub> = 50 mA†	5.5 V				1.65					
I <sub>OL</sub> = 75 mA†	5.5 V						1.65				
I <sub>I</sub>	Data inputs	V <sub>I</sub> = V <sub>CC</sub> or GND	±0.1			±1		±1		μA	
	Control inputs	V <sub>I</sub> = V <sub>CC</sub> or GND	±0.1			±1		±1			
I <sub>OZ</sub> ‡	V <sub>O</sub> = V <sub>CC</sub> or GND, V <sub>I(OE)</sub> = V <sub>IL</sub> or V <sub>IH</sub>		5.5 V	±0.25			±5		±2.5		μA
I <sub>CC</sub>	V <sub>I</sub> = V <sub>CC</sub> or GND, I <sub>O</sub> = 0		5.5 V	4			80		40		μA
C <sub>i</sub>	V <sub>I</sub> = V <sub>CC</sub> or GND		5 V	2.5							pF

† Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.

‡ For I/O ports, the parameter I<sub>OZ</sub> includes the input leakage current.

switching characteristics over recommended operating free-air temperature range, V<sub>CC</sub> = 3.3 V ± 0.3 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	T <sub>A</sub> = 25°C			T <sub>A</sub> = -40°C TO 125°C		T <sub>A</sub> = -40°C TO 85°C		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t <sub>PLH</sub>	A	Y	1.5	6	8	1	11	1	9	ns
t <sub>PHL</sub>			1.5	5.5	8	1	10.5	1	8.5	
t <sub>PZH</sub>	$\overline{OE}$	Y	1.5	6	10.5	1	11.5	1	11	ns
t <sub>PZL</sub>			1.5	7	10	1	13	1	11	
t <sub>PHZ</sub>	$\overline{OE}$	Y	1.5	7	10	1	12.5	1	10.5	ns
t <sub>PLZ</sub>			1.5	7.5	10.5	1	13.5	1	11.5	



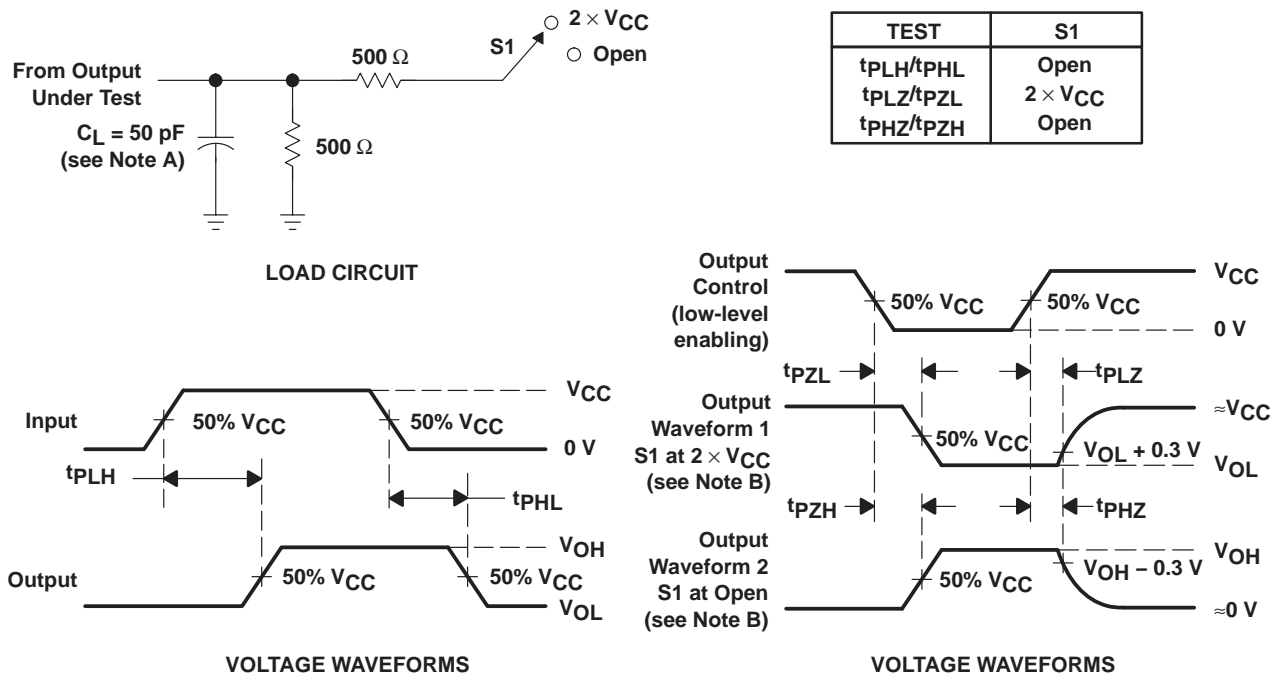
switching characteristics over recommended operating free-air temperature range,  $V_{CC} = 5\text{ V} \pm 0.5\text{ V}$  (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$T_A = 25^\circ\text{C}$			$T_A = -40^\circ\text{C}$ TO $125^\circ\text{C}$		$T_A = -40^\circ\text{C}$ TO $85^\circ\text{C}$		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
$t_{PLH}$	A	Y	1.5	4.5	6.5	1	8.5	1	7	ns
$t_{PHL}$			1.5	4.5	6	1	8	1	6.5	
$t_{PZH}$	$\overline{\text{OE}}$	Y	1.5	5	7	1	9	1	8	ns
$t_{PZL}$			1.5	5.5	8	1	10.5	1	8.5	
$t_{PHZ}$	$\overline{\text{OE}}$	Y	2.5	6.5	9	1	10.5	1	9.5	ns
$t_{PLZ}$			2	6.5	9	1	11	1	9.5	

operating characteristics,  $V_{CC} = 5\text{ V}$ ,  $T_A = 25^\circ\text{C}$

PARAMETER	TEST CONDITIONS	TYP	UNIT
$C_{pd}$ Power dissipation capacitance per buffer/driver	$C_L = 50\text{ pF}$ , $f = 1\text{ MHz}$	45	pF

### PARAMETER MEASUREMENT INFORMATION



- NOTES: A.  $C_L$  includes probe and jig capacitance.  
 B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.  
 C. All input pulses are supplied by generators having the following characteristics:  $PRR \leq 1\text{ MHz}$ ,  $Z_O = 50\ \Omega$ ,  $t_r \leq 2.5\text{ ns}$ ,  $t_f \leq 2.5\text{ ns}$ .  
 D. The outputs are measured one at a time, with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Top-Side Markings (4)	Samples
SN74AC240QPWRG4Q1	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	AC240Q	<a href="#">Samples</a>
SN74AC240QPWRQ1	ACTIVE	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	AC240Q	<a href="#">Samples</a>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) Multiple Top-Side Markings will be inside parentheses. Only one Top-Side Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Top-Side Marking for that device.

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**OTHER QUALIFIED VERSIONS OF SN74AC240-Q1 :**

- Catalog: [SN74AC240](#)
- Military: [SN54AC240](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications

**TAPE AND REEL INFORMATION**

**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74AC240QPWRG4Q1	TSSOP	PW	20	2000	330.0	16.4	6.95	7.1	1.6	8.0	16.0	Q1
SN74AC240QPWRQ1	TSSOP	PW	20	2000	330.0	16.4	6.95	7.1	1.6	8.0	16.0	Q1

**TAPE AND REEL BOX DIMENSIONS**

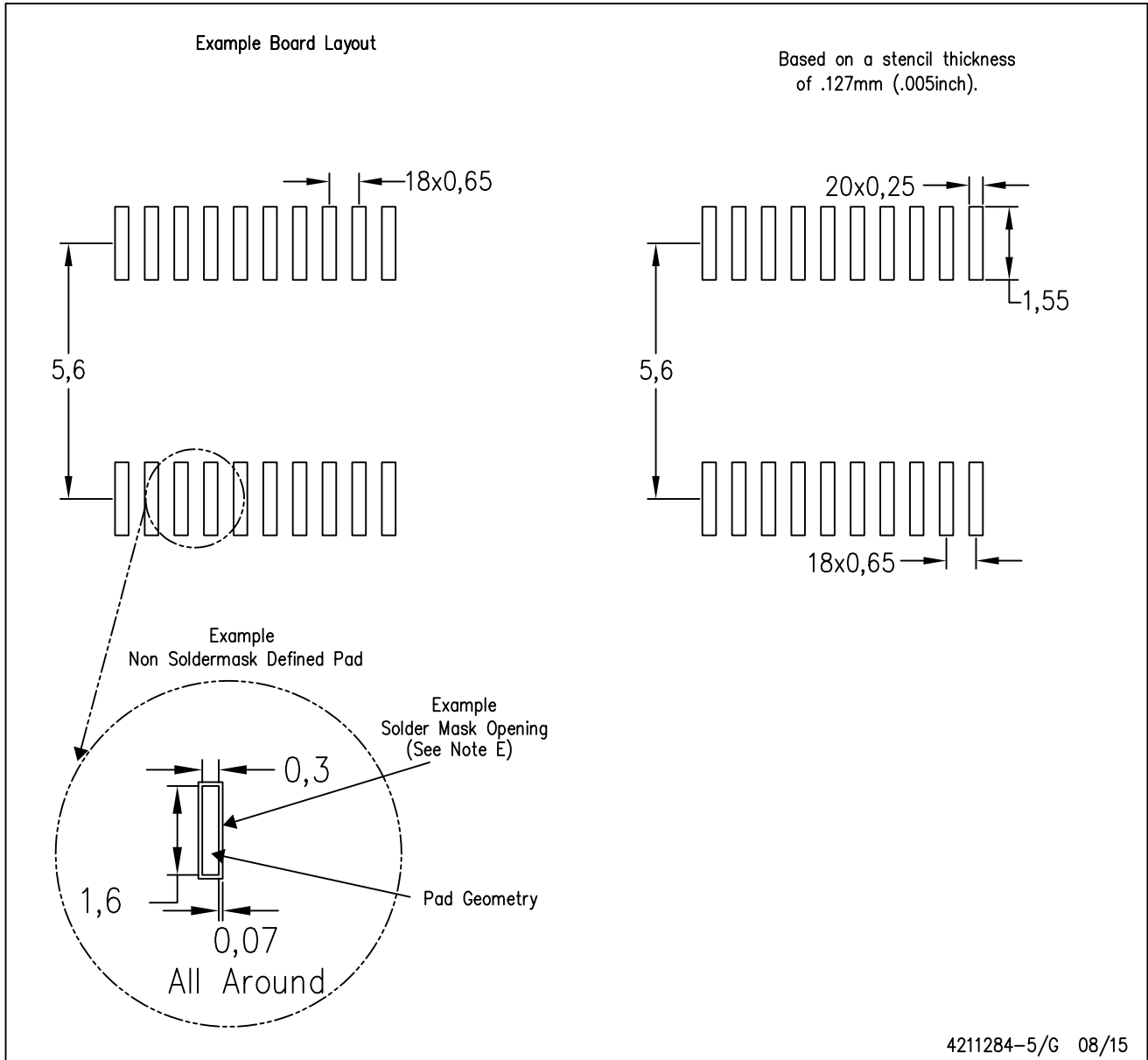

\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74AC240QPWRG4Q1	TSSOP	PW	20	2000	367.0	367.0	38.0
SN74AC240QPWRQ1	TSSOP	PW	20	2000	367.0	367.0	38.0



PW (R-PDSO-G20)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Publication IPC-7351 is recommended for alternate design.
  - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
  - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

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